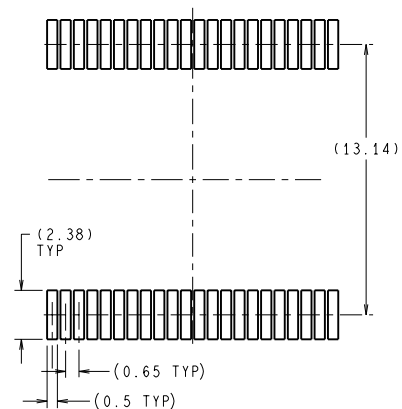
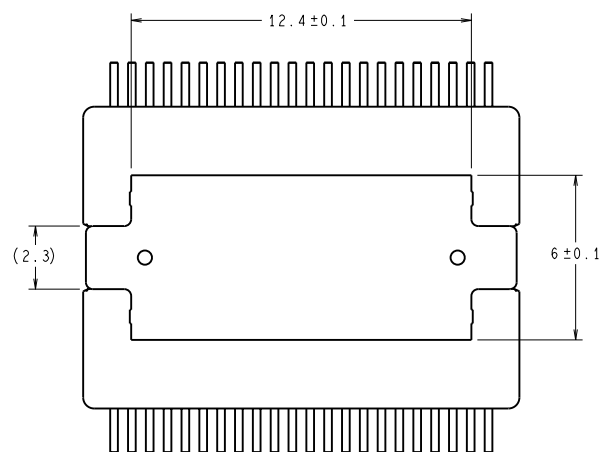
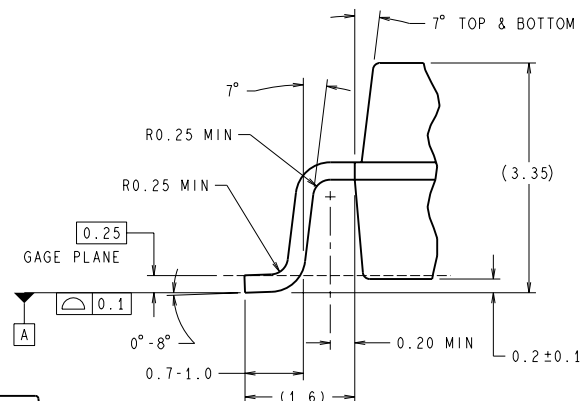




REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11578	09/25/1996	MS/



DETAIL A
TYP, SCALE: 20X

1. STANDARD LEAD FINISH:
7.60 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON COPPER.
2. DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.15mm PER SIDE.
3. NO JEDEC REGISTRATION AS OF SEP.1996.

APPROVALS	DATE	 National Semiconductor 2900 Semiconductor dr. Santa Clara, CA 95052-805			
DRAWN D. E. Grady/M. SUCHY	09/25/1996	MOLDED PSOP, 11.0mm WIDE, 44 LD, 0.65mm PITCH			
DFTG. CHK.					
ENGR. CHK.					
 PROJECTION		SCALE N/A	SIZE C	DRAWING NUMBER (SC)MKT-MWC44A	REV A
 INCH (UNIT)		DO NOT SCALE DRAWING		SHEET 1 of 1	